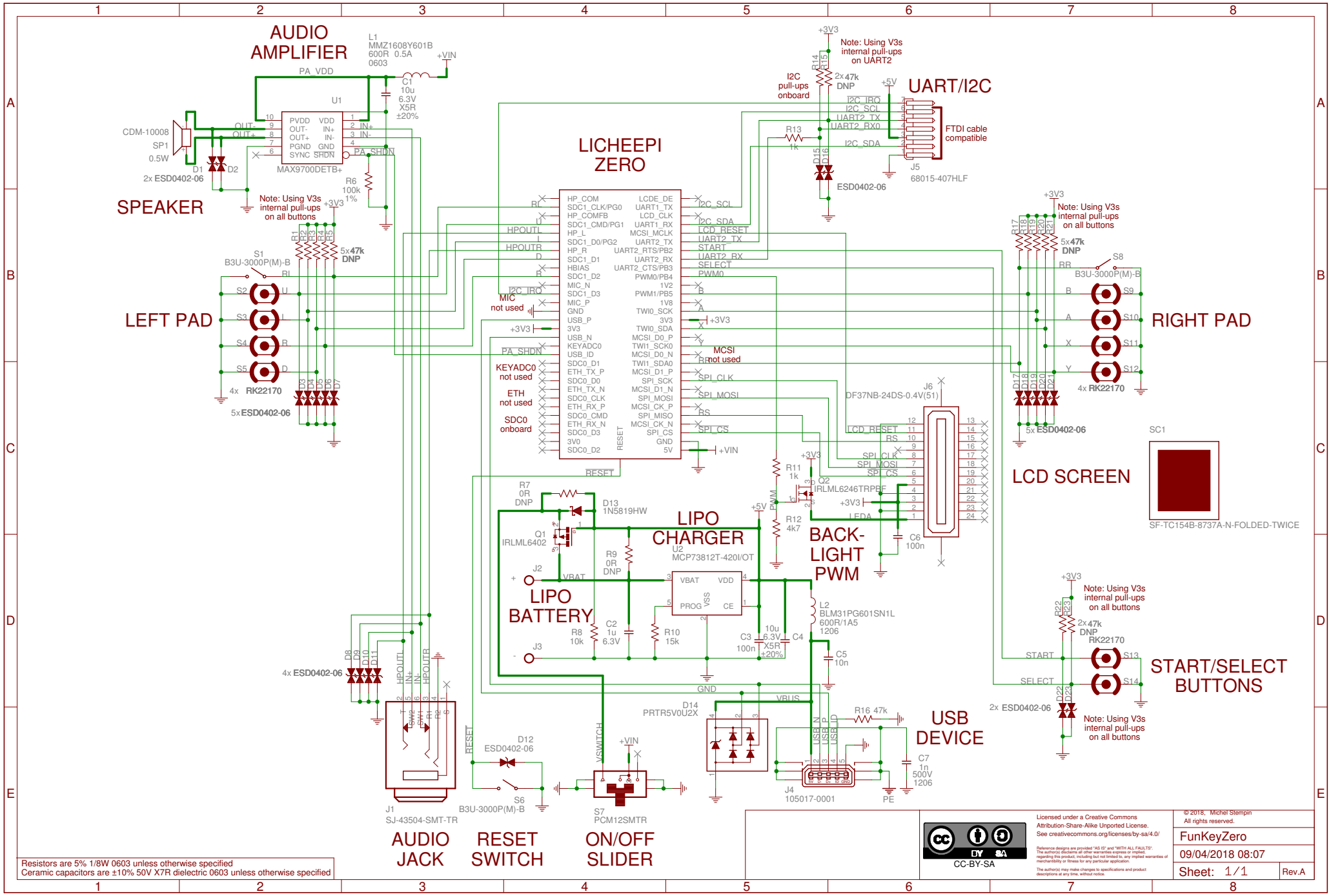
AUDIO AMPLIFIER
L1 MMZ1608Y601B 600R 0.5A 0603
+VIN
PA_VDD
C1 10u 6.3V X5R ±20%
U1
MAX9700DETB+
CDM-10008 SP1 0.5W
D1 D2
2x ESD0402-06
SPEAKER
R6 100k 1%
Note: Using V3s internal pull-ups on all buttons
+3V3
R1 R2 R3 R4 R5 5x 47k DNP
S1 B3U-3000P(M)-B
LEFT PAD
S2 S3 S4 S5
4x RK22170
D3 D4 D5 D6 D7 5x ESD0402-06
LICHEEPI ZERO
HP_COM SDC1_CLK/PG0 HP_COMFB SDC1_CMD/PG1 HP_L SDC1_D0/PG2 HP_R SDC1_D1 HBIAS SDC1_D2 MIC_N SDC1_D3 MIC_P GND USB_P 3V3 USB_N KEYADC0 USB_ID SDC0_D1 ETH_TX_P SDC0_D0 ETH_TX_N SDC0_CLK ETH_RX_P SDC0_CMD ETH_RX_N SDC0_D3 3V0 SDC0_D2
LCDE_DE UART1_TX LCD_CLK UART1_RX MCSI_MCLK UART2_TX UART2_RTS/PB2 UART2_RX UART2_CTS/PB3 PWM0/PB4 1V2 PWM1/PB5 1V8 TWI0_SCK 3V3 TWI0_SDA MCSI_D0_P TWI1_SCK0 MCSI_D0_N TWI1_SDA0 MCSI_D1_P SPI_SCK MCSI_D1_N SPI_MOSI MCSI_CK_P SPI_MISO MCSI_CK_N SPI_CS GND 5V
RESET
I2C_SCL I2C_SDA LCD_RESET UART2_TX START UART2_RX SELECT PWM0 B A +3V3 X Y MCSI not used SPI_CLK SPI_MOSI BS SPI_CS +VIN
I2C_IRQ MIC not used +3V3 PA_SHDN KEYADC0 not used ETH not used SDC0 onboard
UART/I2C
I2C pull-ups onboard
Note: Using V3s internal pull-ups on UART2
R14 R15 2x 47k DNP
R13 1k
D15 D16 ESD0402-06
I2C_IRQ I2C_SCL I2C_SDA UART2_TX UART2_RX
FTDI cable compatible
J5 68015-407HLF
R17 R18 R19 R20 R21 5x 47k DNP
S8 B3U-3000P(M)-B
RIGHT PAD
S9 S10 S11 S12
4x RK22170
D17 D18 D19 D20 D21 5x ESD0402-06
J6 DF37NB-24DS-0.4V(51)
LCD_RESET RS SPI_CLK SPI_MOSI SPI_CS LEDA
LCD SCREEN
SC1
SF-TC154B-8737A-N-FOLDED-TWICE
R11 1k
Q2 IRLML6246TRPBF
R12 4k7
BACK-LIGHT PWM
C6 100n
R7 0R DNP
D13 1N5819HW
Q1 IRLML6402
R9 0R DNP
LIPO CHARGER
U2 MCP73812T-420I/OT
VBAT VDD PROG VSS CE
J2
LIPO BATTERY
J3
R8 10k
C2 1u 6.3V
R10 15k
C3 100n
10u 6.3V X5R ±20%
C4
L2 BLM31PG601SN1L 600R/1A5 1206
C5 10n
GND
VBUS
D14 PRTR5V0U2X
R16 47k
USB_N USB_P USB_ID
J4 105017-0001
PE
C7 1n 500V 1206
USB DEVICE
R22 R23 2x 47k DNP
RK22170
START SELECT
S13 S14
2x ESD0402-06
START/SELECT BUTTONS
Note: Using V3s internal pull-ups on all buttons
4x ESD0402-06
D8 D9 D10 D11
HPOUTL HPOUTR
J1 SJ-43504-SMT-TR
AUDIO JACK
RESET
D12 ESD0402-06
S6 B3U-3000P(M)-B
RESET SWITCH
VSWITCH
+VIN
S7 PCM12SMTR
ON/OFF SLIDER
Resistors are 5% 1/8W 0603 unless otherwise specified
Ceramic capacitors are ±10% 50V X7R dielectric 0603 unless otherwise specified
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The author(s) may make changes to specifications and product descriptions at any time, without notice.
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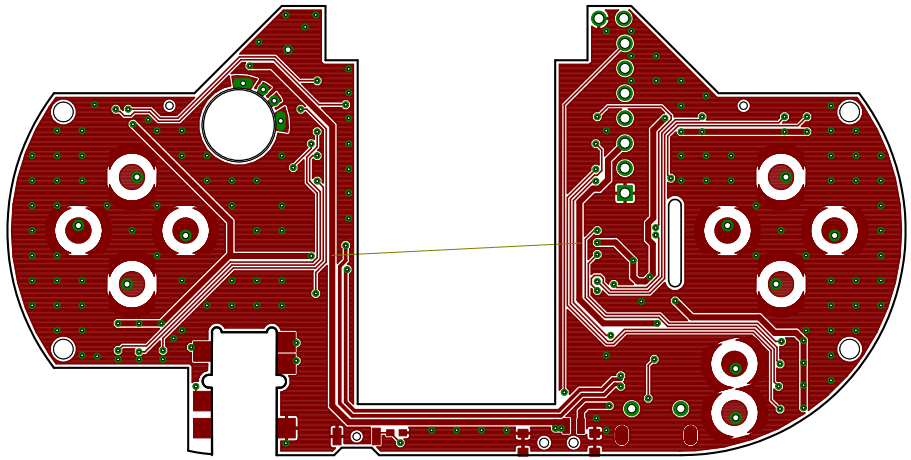
FunKeyZero
09/04/2018 08:07
Sheet: 1/1
Rev.A



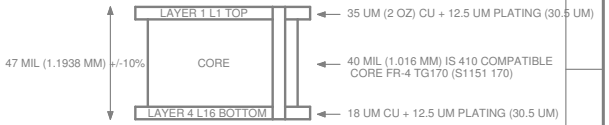
LAYER-STACK

Sym	N°	Mils	MM	Qty	Plated
+	1	12	0.30	186	YES
X	2	20	0.50	4	YES
◫	3	24	0.60	1	YES
◈	4	24	0.61	10	YES
⧖	5	30	0.75	3	NOT
⋈	6	33	0.85	2	YES
⏚	7	35	0.90	2	NOT
ϟ	8	39	1.00	9	YES
✳	9	79	2.00	4	NOT
✳	10	295	7.50	1	NOT

LINE WIDTH IMPEDANCE CHART FOR REFERENCE

Class	RF	Type	Coated Coplanar Waveguide With Ground 1B	
Layer	Impedance	Trace Width	Trace Separation	Ground Separation
TOP, BOTTOM	50 Ohms	28 mils	N/A	6 mils
Class	USB	Type	Diff Coated Coplanar Waveguide With Ground 1B	
Layer	Impedance	Trace Width	Trace Separation	Ground Separation
TOP, BOTTOM	90 Ohms	12 mils	6 mils	6 mils
Class	Ethernet	Type	Diff Coated Coplanar Waveguide With Ground 1B	
Layer	Impedance	Trace Width	Trace Separation	Ground Separation
TOP, BOTTOM	100 Ohms	9 mils	6 mils	6 mils

STACK-UP FOR REFERENCE



NOTES:

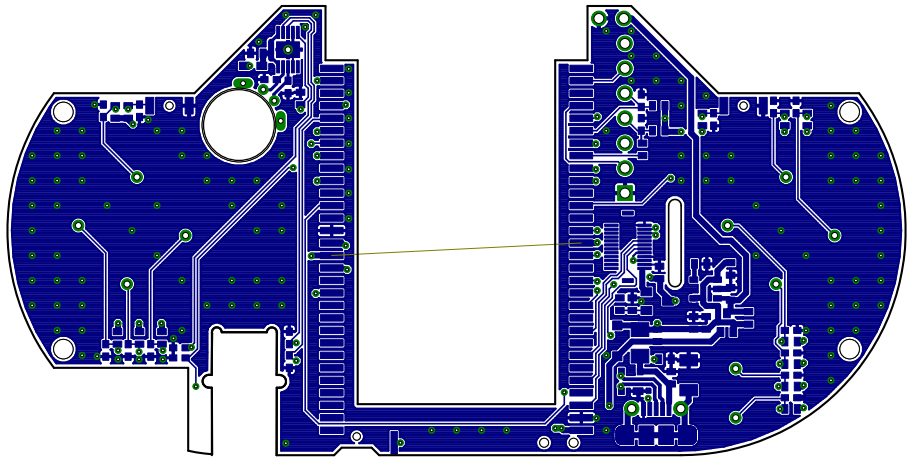
1. PRINTED CIRCUIT BOARD MADE FROM NEMA GRADE FR-4 TG 170 EPOXY LAMINATE WITH 18 UM COPPER PLATING AND 1.2 MM THICKNESS.
2. ALL DIMENSIONS ARE GIVEN IN MILLIMETERS EXCEPT TRACE WIDTH/SPACE.
3. CIRCUIT PATHS ARE FOR REFERENCE ONLY.
4. HOLE SIZES SHOWN ARE FINISHED DIAMETERS AFTER PLATING.
5. BOARD PLATED USING REFLOW OR SIMILAR METHOD.
6. BOARD TO HAVE GREEN SOLDER MASK ON PLATED SURFACES USING WET FILM SR100 OR SR1010 EPOXY. EQUIVALENT WET OR DRY FILM MAY BE USED.
7. SILKSCREEN BOARD USING WHITE INK. DISTORTION OF SILKSCREEN IS ACCEPTABLE OVER TRACES. EPOXY INK ON PLATED LANDS IS NOT ACCEPTABLE
8. THE FOLLOWING INFORMATION APPLIES TO THIS BOARD:
   * 2 COPPER LAYERS
   * 1.2 MM BOARD THICKNESS
   * REQUIRES TOP AND BOTTOM SIDE SILKSCREENS

FunKeyZero

not saved!

Component side (.CMP)

Rev. A



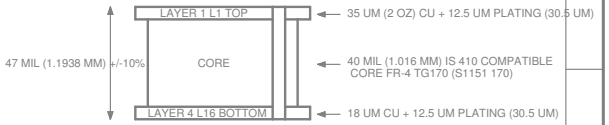
LAYER-STACK

Sym	N°	Mils	MM	Qty	Plated
+	1	12	0.30	186	YES
×	2	20	0.50	4	YES
◫	3	24	0.60	1	YES
◇	4	24	0.61	10	YES
⧖	5	30	0.75	3	NOT
⋈	6	33	0.85	2	YES
⇳	7	35	0.90	2	NOT
ϟ	8	39	1.00	9	YES
✳	9	79	2.00	4	NOT
✳	10	295	7.50	1	NOT

LINE WIDTH IMPEDANCE CHART FOR REFERENCE

Class	RF	Type	Coated Coplanar Waveguide With Ground 1B	
Layer	Impedance	Trace Width	Trace Separation	Ground Separation
TOP, BOTTOM	50 Ohms	28 mils	N/A	6 mils
Class	USB	Type	Diff Coated Coplanar Waveguide With Ground 1B	
Layer	Impedance	Trace Width	Trace Separation	Ground Separation
TOP, BOTTOM	90 Ohms	12 mils	6 mils	6 mils
Class	Ethernet	Type	Diff Coated Coplanar Waveguide With Ground 1B	
Layer	Impedance	Trace Width	Trace Separation	Ground Separation
TOP, BOTTOM	100 Ohms	9 mils	6 mils	6 mils

STACK-UP FOR REFERENCE



NOTES:

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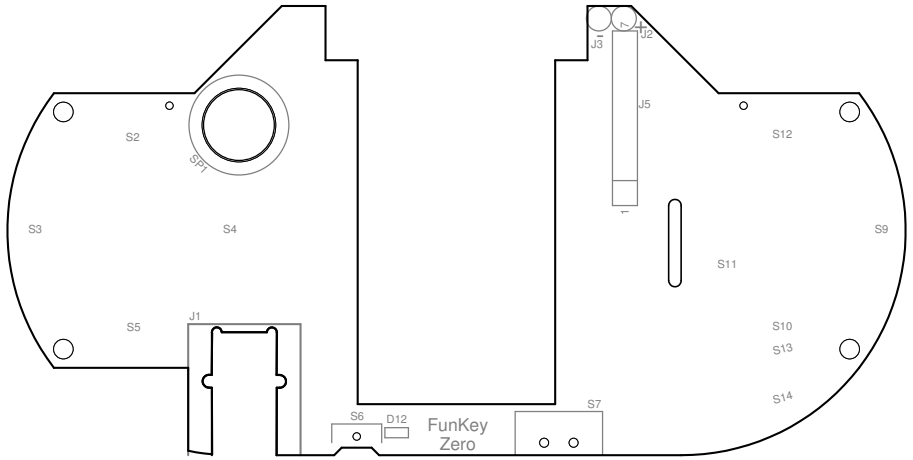
3. CIRCUIT PATHS ARE FOR REFERENCE ONLY.
4. HOLE SIZES SHOWN ARE FINISHED DIAMETERS AFTER PLATING.
5. BOARD PLATED USING REFLOW OR SIMILAR METHOD.
6. BOARD TO HAVE GREEN SOLDER MASK ON PLATED SURFACES USING WET FILM SR100 OR SR1010 EPOXY. EQUIVALENT WET OR DRY FILM MAY BE USED.
7. SILKSCREEN BOARD USING WHITE INK. DISTORTION OF SILKSCREEN IS ACCEPTABLE OVER TRACES. EPOXY INK ON PLATED LANDS IS NOT ACCEPTABLE
8. THE FOLLOWING INFORMATION APPLIES TO THIS BOARD:
   * 2 COPPER LAYERS
   * 1.2 MM BOARD THICKNESS
   * REQUIRES TOP AND BOTTOM SIDE SILKSCREENS

FunKeyZero

not saved!

Solder Side (.SOL)

Rev. A



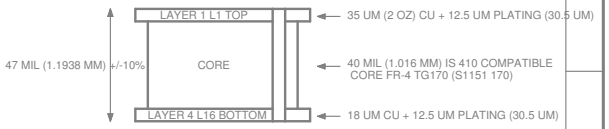
LAYER-STACK

Sym	N°	Mils	MM	Qty	Plated
+	1	12	0.30	186	YES
×	2	20	0.50	4	YES
◫	3	24	0.60	1	YES
◈	4	24	0.61	10	YES
⧖	5	30	0.75	3	NOT
⋈	6	33	0.85	2	YES
⇳	7	35	0.90	2	NOT
ϟ	8	39	1.00	9	YES
✳	9	79	2.00	4	NOT
✳	10	295	7.50	1	NOT

LINE WIDTH IMPEDANCE CHART FOR REFERENCE

Class	RF	Type	Coated Coplanar Waveguide With Ground 1B	
Layer	Impedance	Trace Width	Trace Separation	Ground Separation
TOP, BOTTOM	50 Ohms	28 mils	N/A	6 mils
Class	USB	Type	Diff Coated Coplanar Waveguide With Ground 1B	
Layer	Impedance	Trace Width	Trace Separation	Ground Separation
TOP, BOTTOM	90 Ohms	12 mils	6 mils	6 mils
Class	Ethernet	Type	Diff Coated Coplanar Waveguide With Ground 1B	
Layer	Impedance	Trace Width	Trace Separation	Ground Separation
TOP, BOTTOM	100 Ohms	9 mils	6 mils	6 mils

STACK-UP FOR REFERENCE



NOTES:

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3. CIRCUIT PATHS ARE FOR REFERENCE ONLY.
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5. BOARD PLATED USING REFLOW OR SIMILAR METHOD.
6. BOARD TO HAVE GREEN SOLDER MASK ON PLATED SURFACES USING WET FILM SR100 OR SR1010 EPOXY. EQUIVALENT WET OR DRY FILM MAY BE USED.
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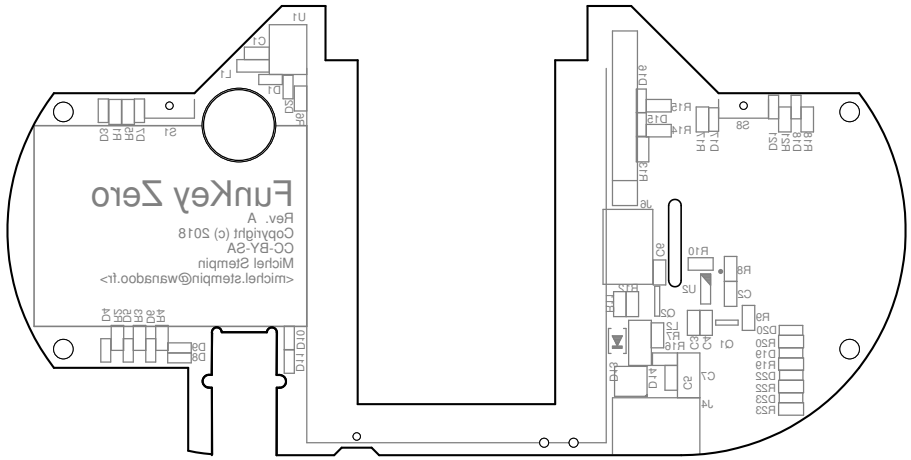
8. THE FOLLOWING INFORMATION APPLIES TO THIS BOARD:
   * 2 COPPER LAYERS
   * 1.2 MM BOARD THICKNESS
   * REQUIRES TOP AND BOTTOM SIDE SILKSCREENS

FunKeyZero

not saved!

Rev. A



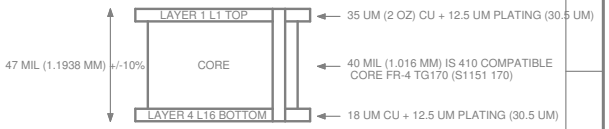
LAYER-STACK

Sym	N°	Mils	MM	Qty	Plated
+	1	12	0.30	186	YES
×	2	20	0.50	4	YES
□	3	24	0.60	1	YES
◇	4	24	0.61	10	YES
⧖	5	30	0.75	3	NOT
⋈	6	33	0.85	2	YES
⊹	7	35	0.90	2	NOT
ϟ	8	39	1.00	9	YES
⊠	9	79	2.00	4	NOT
⊗	10	295	7.50	1	NOT

LINE WIDTH IMPEDANCE CHART FOR REFERENCE

Class	RF	Type	Coated Coplanar Waveguide With Ground 1B	
Layer	Impedance	Trace Width	Trace Separation	Ground Separation
TOP, BOTTOM	50 Ohms	28 mils	N/A	6 mils
Class	USB	Type	Diff Coated Coplanar Waveguide With Ground 1B	
Layer	Impedance	Trace Width	Trace Separation	Ground Separation
TOP, BOTTOM	90 Ohms	12 mils	6 mils	6 mils
Class	Ethernet	Type	Diff Coated Coplanar Waveguide With Ground 1B	
Layer	Impedance	Trace Width	Trace Separation	Ground Separation
TOP, BOTTOM	100 Ohms	9 mils	6 mils	6 mils

STACK-UP FOR REFERENCE



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   * 1.2 MM BOARD THICKNESS
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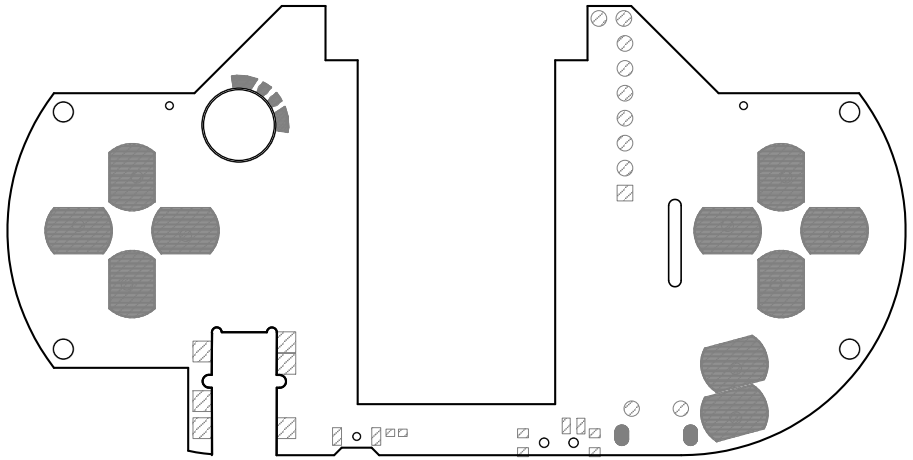
FunKeyZero

not saved!

Rev. A



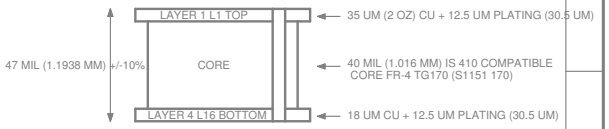
LAYER-STACK

Sym	N°	Mils	MM	Qty	Plated
┼	1	12	0.30	186	YES
╳	2	20	0.50	4	YES
◫	3	24	0.60	1	YES
◈	4	24	0.61	10	YES
⧖	5	30	0.75	3	NOT
⋈	6	33	0.85	2	YES
⇳	7	35	0.90	2	NOT
ϟ	8	39	1.00	9	YES
✳	9	79	2.00	4	NOT
✳	10	295	7.50	1	NOT

LINE WIDTH IMPEDANCE CHART FOR REFERENCE

Class	RF	Type	Coated Coplanar Waveguide With Ground 1B	
Layer	Impedance	Trace Width	Trace Separation	Ground Separation
TOP, BOTTOM	50 Ohms	28 mils	N/A	6 mils
Class	USB	Type	Diff Coated Coplanar Waveguide With Ground 1B	
Layer	Impedance	Trace Width	Trace Separation	Ground Separation
TOP, BOTTOM	90 Ohms	12 mils	6 mils	6 mils
Class	Ethernet	Type	Diff Coated Coplanar Waveguide With Ground 1B	
Layer	Impedance	Trace Width	Trace Separation	Ground Separation
TOP, BOTTOM	100 Ohms	9 mils	6 mils	6 mils

STACK-UP FOR REFERENCE



NOTES:

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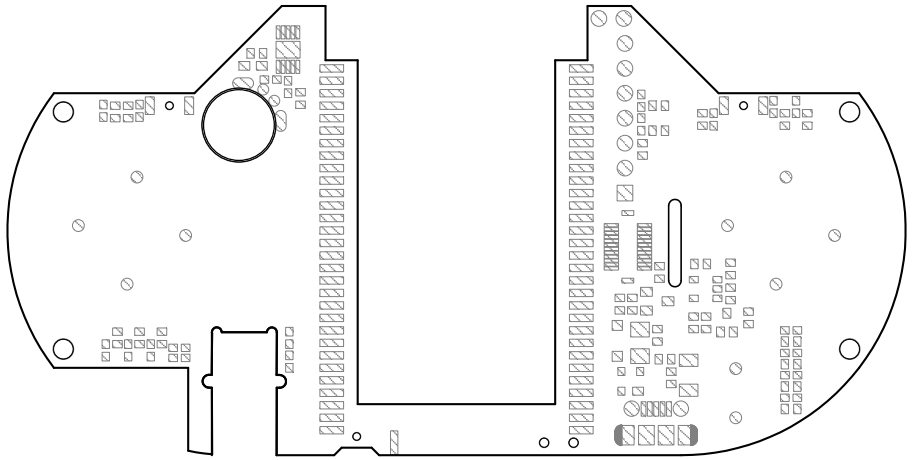
   * REQUIRES TOP AND BOTTOM SIDE SILKSCREENS

FunKeyZero

not saved!

Solder stop mask CMP (.STC) | Rev. A



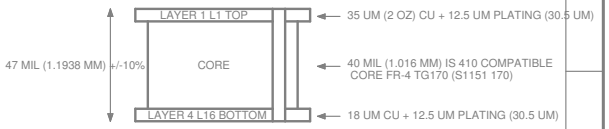
LAYER-STACK

Sym	N°	Mils	MM	Qty	Plated
┼	1	12	0.30	186	YES
╳	2	20	0.50	4	YES
◫	3	24	0.60	1	YES
◈	4	24	0.61	10	YES
⧖	5	30	0.75	3	NOT
⋈	6	33	0.85	2	YES
⇳	7	35	0.90	2	NOT
ϟ	8	39	1.00	9	YES
✳	9	79	2.00	4	NOT
✳	10	295	7.50	1	NOT

LINE WIDTH IMPEDANCE CHART FOR REFERENCE

Class	RF	Type	Coated Coplanar Waveguide With Ground 1B	
Layer	Impedance	Trace Width	Trace Separation	Ground Separation
TOP, BOTTOM	50 Ohms	28 mils	N/A	6 mils
Class	USB	Type	Diff Coated Coplanar Waveguide With Ground 1B	
Layer	Impedance	Trace Width	Trace Separation	Ground Separation
TOP, BOTTOM	90 Ohms	12 mils	6 mils	6 mils
Class	Ethernet	Type	Diff Coated Coplanar Waveguide With Ground 1B	
Layer	Impedance	Trace Width	Trace Separation	Ground Separation
TOP, BOTTOM	100 Ohms	9 mils	6 mils	6 mils

STACK-UP FOR REFERENCE



NOTES:

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3. CIRCUIT PATHS ARE FOR REFERENCE ONLY.
4. HOLE SIZES SHOWN ARE FINISHED DIAMETERS AFTER PLATING.
5. BOARD PLATED USING REFLOW OR SIMILAR METHOD.
6. BOARD TO HAVE GREEN SOLDER MASK ON PLATED SURFACES USING WET FILM SR100 OR SR1010 EPOXY. EQUIVALENT WET OR DRY FILM MAY BE USED.
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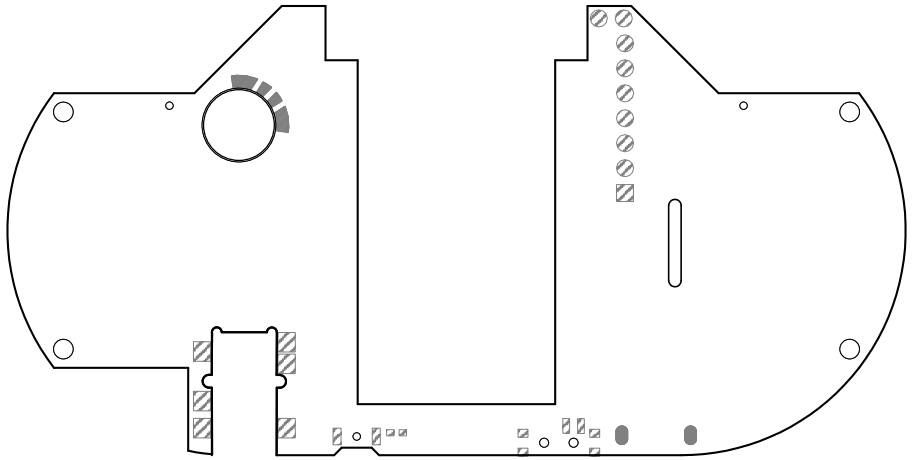
8. THE FOLLOWING INFORMATION APPLIES TO THIS BOARD:
   * 2 COPPER LAYERS
   * 1.2 MM BOARD THICKNESS
   * REQUIRES TOP AND BOTTOM SIDE SILKSCREENS

FunKeyZero

not saved!

Solder stop mask SOL (.STS) | Rev. A



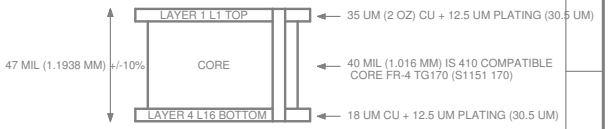
LAYER-STACK

Sym	N°	Mils	MM	Qty	Plated
┼	1	12	0.30	186	YES
╳	2	20	0.50	4	YES
◫	3	24	0.60	1	YES
◈	4	24	0.61	10	YES
⧖	5	30	0.75	3	NOT
⋈	6	33	0.85	2	YES
⏚	7	35	0.90	2	NOT
ϟ	8	39	1.00	9	YES
✳	9	79	2.00	4	NOT
✳	10	295	7.50	1	NOT

LINE WIDTH IMPEDANCE CHART FOR REFERENCE

Class	RF	Type	Coated Coplanar Waveguide With Ground 1B	
Layer	Impedance	Trace Width	Trace Separation	Ground Separation
TOP, BOTTOM	50 Ohms	28 mils	N/A	6 mils
Class	USB	Type	Diff Coated Coplanar Waveguide With Ground 1B	
Layer	Impedance	Trace Width	Trace Separation	Ground Separation
TOP, BOTTOM	90 Ohms	12 mils	6 mils	6 mils
Class	Ethernet	Type	Diff Coated Coplanar Waveguide With Ground 1B	
Layer	Impedance	Trace Width	Trace Separation	Ground Separation
TOP, BOTTOM	100 Ohms	9 mils	6 mils	6 mils

STACK-UP FOR REFERENCE



NOTES:

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3. CIRCUIT PATHS ARE FOR REFERENCE ONLY.
4. HOLE SIZES SHOWN ARE FINISHED DIAMETERS AFTER PLATING.
5. BOARD PLATED USING REFLOW OR SIMILAR METHOD.
6. BOARD TO HAVE GREEN SOLDER MASK ON PLATED SURFACES USING WET FILM SR100 OR SR1010 EPOXY. EQUIVALENT WET OR DRY FILM MAY BE USED.
7. SILKSCREEN BOARD USING WHITE INK. DISTORTION OF SILKSCREEN IS ACCEPTABLE OVER TRACES. EPOXY INK ON PLATED LANDS IS NOT ACCEPTABLE
8. THE FOLLOWING INFORMATION APPLIES TO THIS BOARD:
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   * 1.2 MM BOARD THICKNESS
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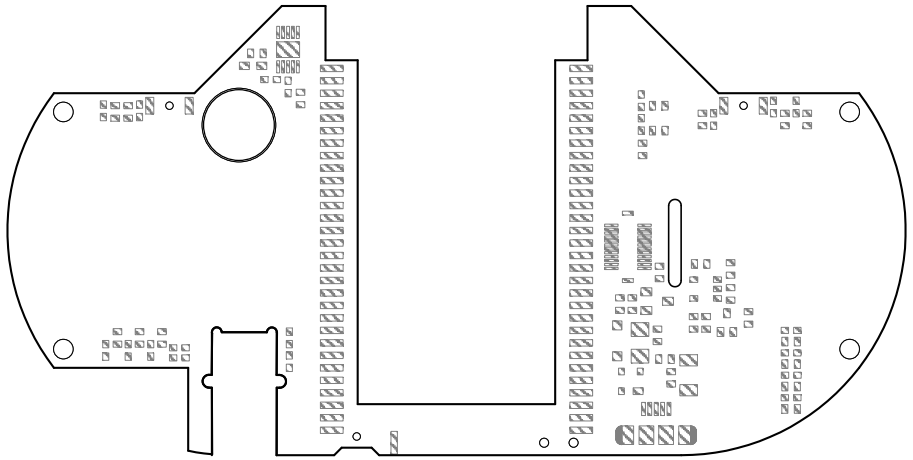
FunKeyZero

not saved!

Cream frame CMP (.CRC) | Rev. A



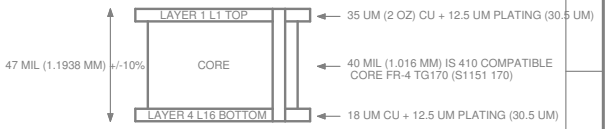
LAYER-STACK

Sym	N°	Mils	MM	Qty	Plated
┼	1	12	0.30	186	YES
╳	2	20	0.50	4	YES
◫	3	24	0.60	1	YES
◈	4	24	0.61	10	YES
⧖	5	30	0.75	3	NOT
⋈	6	33	0.85	2	YES
⏚	7	35	0.90	2	NOT
ϟ	8	39	1.00	9	YES
✳	9	79	2.00	4	NOT
✳	10	295	7.50	1	NOT

LINE WIDTH IMPEDANCE CHART FOR REFERENCE

Class	RF	Type	Coated Coplanar Waveguide With Ground 1B	
Layer	Impedance	Trace Width	Trace Separation	Ground Separation
TOP, BOTTOM	50 Ohms	28 mils	N/A	6 mils
Class	USB	Type	Diff Coated Coplanar Waveguide With Ground 1B	
Layer	Impedance	Trace Width	Trace Separation	Ground Separation
TOP, BOTTOM	90 Ohms	12 mils	6 mils	6 mils
Class	Ethernet	Type	Diff Coated Coplanar Waveguide With Ground 1B	
Layer	Impedance	Trace Width	Trace Separation	Ground Separation
TOP, BOTTOM	100 Ohms	9 mils	6 mils	6 mils

STACK-UP FOR REFERENCE



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5. BOARD PLATED USING REFLOW OR SIMILAR METHOD.
6. BOARD TO HAVE GREEN SOLDER MASK ON PLATED SURFACES USING WET FILM SR100 OR SR1010 EPOXY. EQUIVALENT WET OR DRY FILM MAY BE USED.
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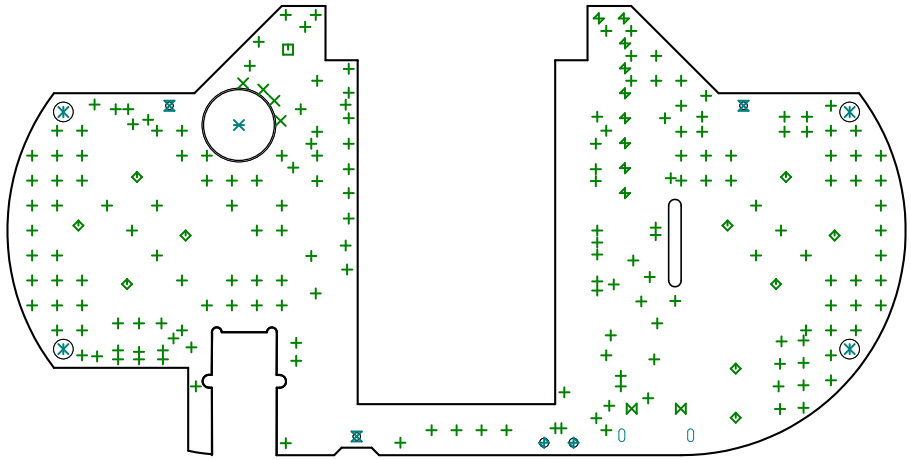
   * 1.2 MM BOARD THICKNESS
   * REQUIRES TOP AND BOTTOM SIDE SILKSCREENS

FunKeyZero

not saved!

Cream frame SOL (.CRS) | Rev. A



01-16
01-20

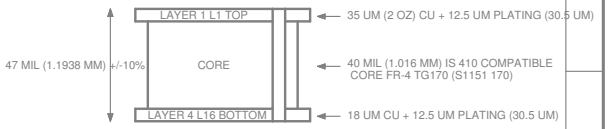
LAYER-STACK

Sym	N°	Mils	MM	Qty	Plated
+	1	12	0.30	186	YES
×	2	20	0.50	4	YES
□	3	24	0.60	1	YES
◇	4	24	0.61	10	YES
⧖	5	30	0.75	3	NOT
⋈	6	33	0.85	2	YES
⊹	7	35	0.90	2	NOT
ϟ	8	39	1.00	9	YES
✳	9	79	2.00	4	NOT
✳	10	295	7.50	1	NOT

LINE WIDTH IMPEDANCE CHART FOR REFERENCE

Class	RF	Type	Coated Coplanar Waveguide With Ground 1B	
Layer	Impedance	Trace Width	Trace Separation	Ground Separation
TOP, BOTTOM	50 Ohms	28 mils	N/A	6 mils
Class	USB	Type	Diff Coated Coplanar Waveguide With Ground 1B	
Layer	Impedance	Trace Width	Trace Separation	Ground Separation
TOP, BOTTOM	90 Ohms	12 mils	6 mils	6 mils
Class	Ethernet	Type	Diff Coated Coplanar Waveguide With Ground 1B	
Layer	Impedance	Trace Width	Trace Separation	Ground Separation
TOP, BOTTOM	100 Ohms	9 mils	6 mils	6 mils

STACK-UP FOR REFERENCE



NOTES:

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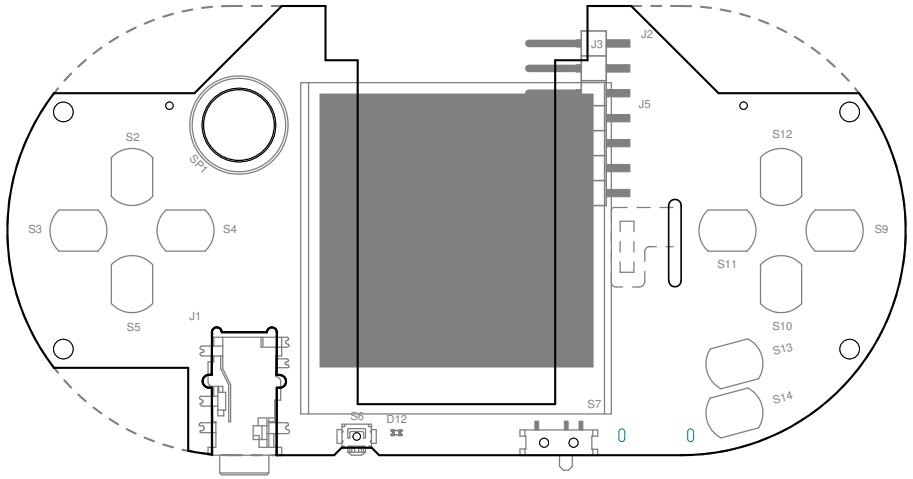
FunKeyZero

not saved!

Drill data (.DRD)

Rev. A



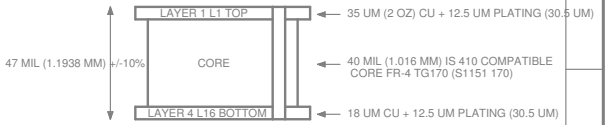
LAYER-STACK

Sym	N°	Mils	MM	Qty	Plated
+	1	12	0.30	186	YES
×	2	20	0.50	4	YES
◫	3	24	0.60	1	YES
◈	4	24	0.61	10	YES
⧖	5	30	0.75	3	NOT
⋈	6	33	0.85	2	YES
⊹	7	35	0.90	2	NOT
ϟ	8	39	1.00	9	YES
✳	9	79	2.00	4	NOT
✳	10	295	7.50	1	NOT

LINE WIDTH IMPEDANCE CHART FOR REFERENCE

Class	RF	Type	Coated Coplanar Waveguide With Ground 1B	
Layer	Impedance	Trace Width	Trace Separation	Ground Separation
TOP, BOTTOM	50 Ohms	28 mils	N/A	6 mils
Class	USB	Type	Diff Coated Coplanar Waveguide With Ground 1B	
Layer	Impedance	Trace Width	Trace Separation	Ground Separation
TOP, BOTTOM	90 Ohms	12 mils	6 mils	6 mils
Class	Ethernet	Type	Diff Coated Coplanar Waveguide With Ground 1B	
Layer	Impedance	Trace Width	Trace Separation	Ground Separation
TOP, BOTTOM	100 Ohms	9 mils	6 mils	6 mils

STACK-UP FOR REFERENCE



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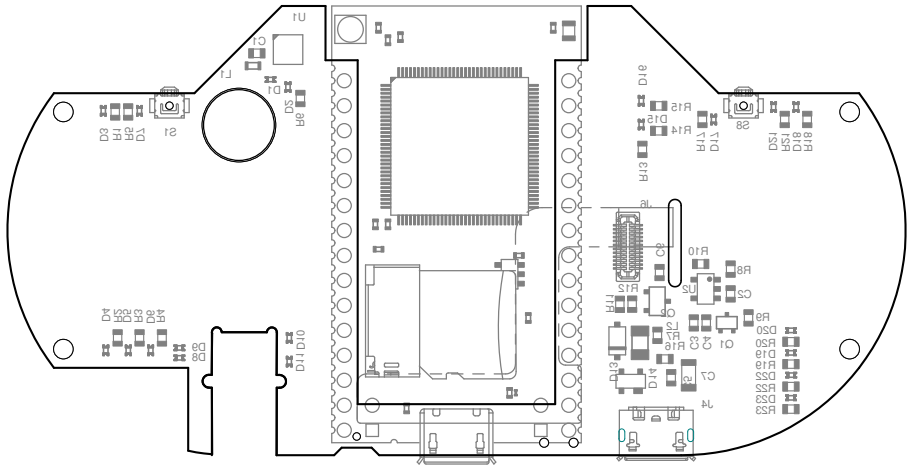
FunKeyZero

not saved!

Component Assembly CMP (.ASC) | Rev. A



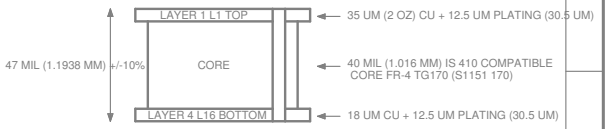
LAYER-STACK

Sym	N°	Mils	MM	Qty	Plated
+	1	12	0.30	186	YES
×	2	20	0.50	4	YES
◻	3	24	0.60	1	YES
◇	4	24	0.61	10	YES
⧖	5	30	0.75	3	NOT
⋈	6	33	0.85	2	YES
⊹	7	35	0.90	2	NOT
ϟ	8	39	1.00	9	YES
✳	9	79	2.00	4	NOT
✳	10	295	7.50	1	NOT

LINE WIDTH IMPEDANCE CHART FOR REFERENCE

Class	RF	Type	Coated Coplanar Waveguide With Ground 1B	
Layer	Impedance	Trace Width	Trace Separation	Ground Separation
TOP, BOTTOM	50 Ohms	28 mils	N/A	6 mils
Class	USB	Type	Diff Coated Coplanar Waveguide With Ground 1B	
Layer	Impedance	Trace Width	Trace Separation	Ground Separation
TOP, BOTTOM	90 Ohms	12 mils	6 mils	6 mils
Class	Ethernet	Type	Diff Coated Coplanar Waveguide With Ground 1B	
Layer	Impedance	Trace Width	Trace Separation	Ground Separation
TOP, BOTTOM	100 Ohms	9 mils	6 mils	6 mils

STACK-UP FOR REFERENCE



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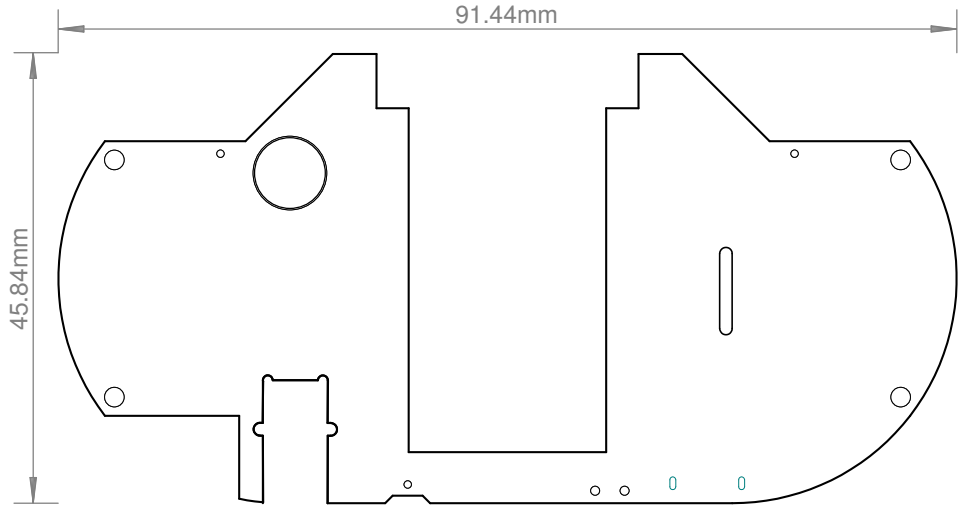
FunKeyZero

not saved!

Component Assembly SOL (.ASS) | Rev. A



LAYER-STACK

Sym	N°	Mils	MM	Qty	Plated
┼	1	12	0.30	186	YES
╳	2	20	0.50	4	YES
◫	3	24	0.60	1	YES
◈	4	24	0.61	10	YES
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✳	10	295	7.50	1	NOT

LINE WIDTH IMPEDANCE CHART FOR REFERENCE

Class	RF	Type	Coated Coplanar Waveguide With Ground 1B	
Layer	Impedance	Trace Width	Trace Separation	Ground Separation
TOP, BOTTOM	50 Ohms	28 mils	N/A	6 mils
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Layer	Impedance	Trace Width	Trace Separation	Ground Separation
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Class	Ethernet	Type	Diff Coated Coplanar Waveguide With Ground 1B	
Layer	Impedance	Trace Width	Trace Separation	Ground Separation
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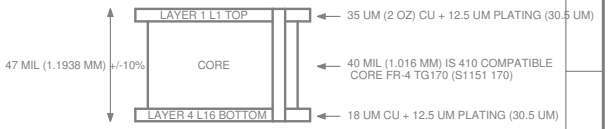
STACK-UP FOR REFERENCE



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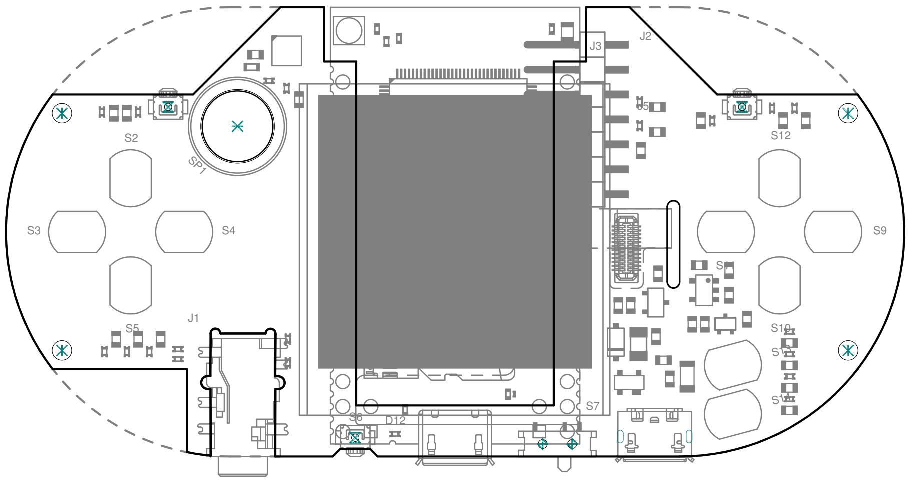
FunKeyZero

not saved!

Rev. A

01-20



LAYER-STACK

Sym	N°	Mils	MM	Qty	Plated
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LINE WIDTH IMPEDANCE CHART FOR REFERENCE

Class	RF	Type	Coated Coplanar Waveguide With Ground 1B	
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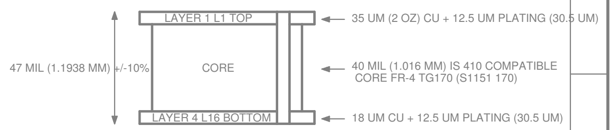

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FunKeyZero

not saved!

Component Assembly SMP (ASS) / Outline (OLA)

Rev. A